

# PATENT ABSTRACTS OF JAPAN

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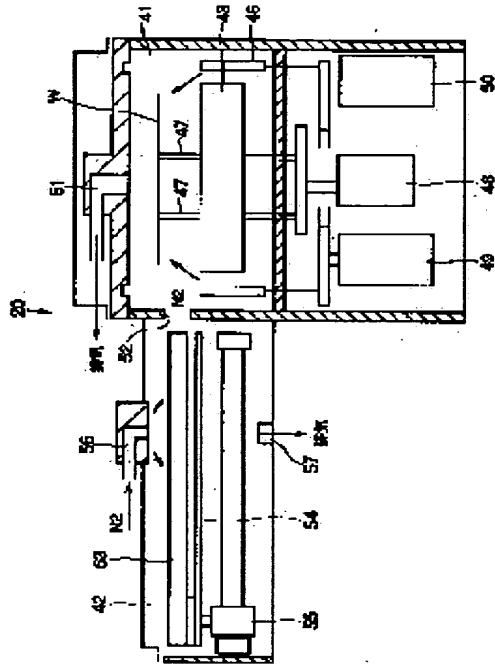
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(54) COATING FILM FORMING APPARATUS AND HARDENING APPARATUS

**(57)Abstract:**

**PROBLEM TO BE SOLVED:** To provide a coating film forming apparatus and a curing apparatus which can manage substrates on which coating films are formed for each substrate at curing the coating films and, in addition, can prevent oxidation of the coating films.

**SOLUTION:** A DCC treatment unit 20 has a heat treating chamber 41, in which a wafer W is heated and a cooling chamber 42 which communicates with the heat treating chamber 41 and in which the heated wafer W is cooled. The wafer W is heat treated and cooled in an atmosphere containing oxygen at low concentration by evacuating the communicated chambers 41 and 42, while inert gas is supplied to the chambers 41 and 42.



## LEGAL STATUS

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